KM2520SGD08 SUPER BRIGHT GREEN

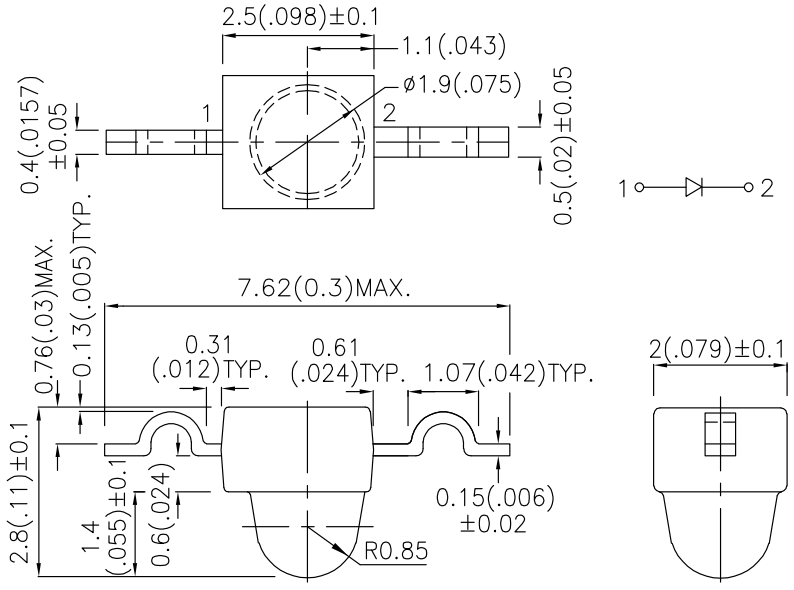
Features

- ●SUBMINIATURE PACKAGE.
- ●WIDE VIEWING ANGLE.
- ●YOKE LEAD.
- ●LONG LIFE - SOLID STATE RELIABILITY.
- ●LOW PACKAGE PROFILE.
- ●PACKAGE : 1000PCS / REEL.
- ●RoHS COMPLIANT.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
KM2520SGD08	SUPER BRIGHT GREEN (GaP)	GREEN DIFFUSED	2.6	10	40°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

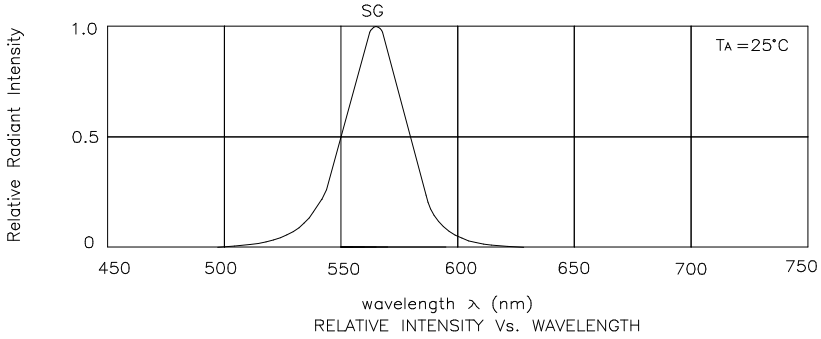
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	I_F=20mA
λD	Dominant Wavelength	Super Bright Green	568		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	I_F=20mA
C	Capacitance	Super Bright Green	15		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Super Bright Green	2.2	2.5	V	I_F=20mA
I_R	Reverse Current	Super Bright Green		10	uA	V_R= 5V

Absolute Maximum Ratings at T_A=25°C

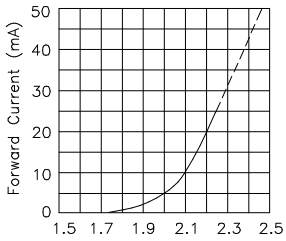
Parameter	Super Bright Green	Units
Power dissipation	105	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

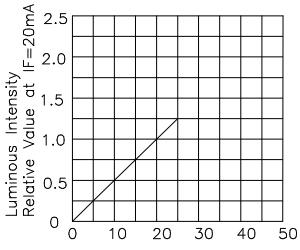


RELATIVE INTENSITY Vs. WAVELENGTH

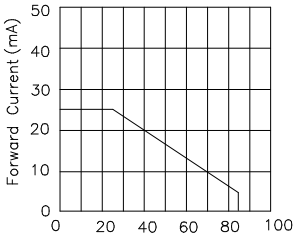
Super Bright Green **KM2520SGD08**



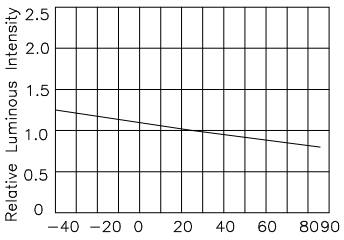
FORWARD CURRENT Vs.
FORWARD VOLTAGE



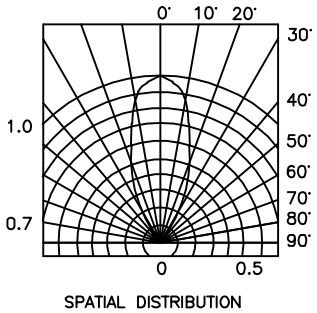
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



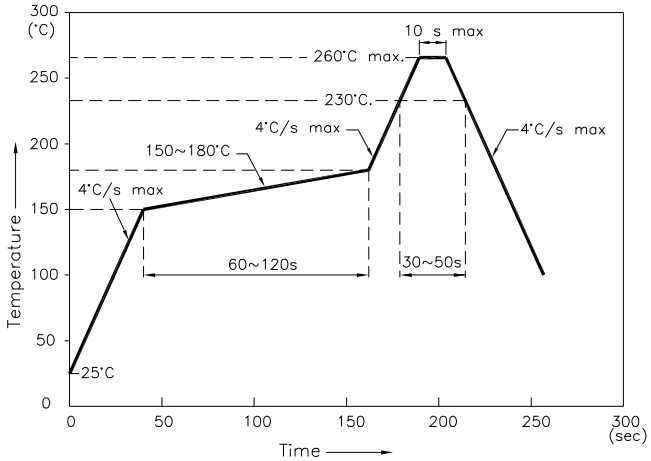
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

KM2520SGD08

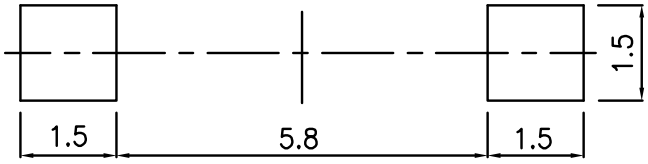
Reflow Soldering Profile For Lead-free SMT Process.



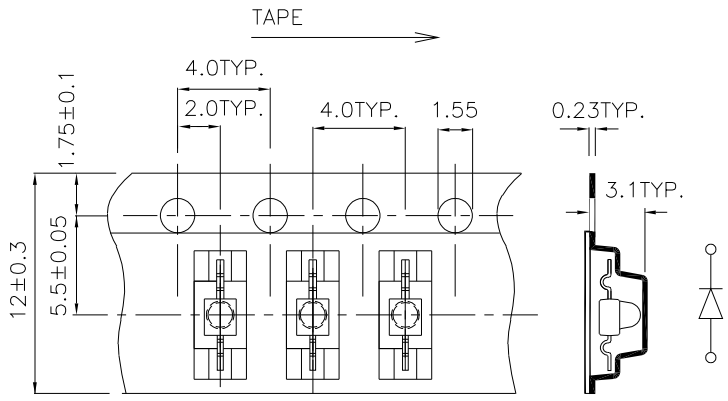
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.